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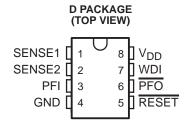
- Qualified for Automotive Applications
- Dual Supervisory Circuits With Power Fail for DSP and Processor-Based Systems
- Voltage Monitor for Power Fail or Low-Battery Warning
- Watchdog Timer With 0.8-s Time-Out
- Power-On Reset Generator With Integrated 100-ms Delay Time
- Open-Drain Reset and Power-Fail Output
- Supply Current of 15 μA (Typ)

description

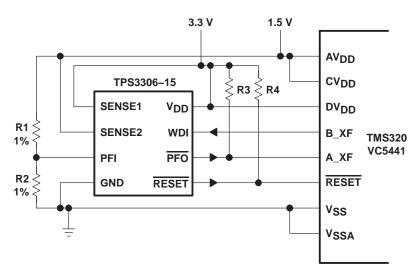
The TPS3306 family is a series of supervisory circuits designed for circuit initialization, which require two supply voltages, primarily in DSP and processor-based systems.

The product spectrum of the TPS3306-xx is designed for monitoring two independent supply voltages of 3.3 V/1.5 V, 3.3 V/1.8 V, 3.3 V/2 V, 3.3 V/2.5 V, or 3.3 V/5 V.

- Supply Voltage Range . . . 2.7 V to 6 V
- Defined RESET Output From $V_{DD} \ge 1.1 \text{ V}$
- SO-8 Package
- Temperature Range . . . –40°C to 125°C
- Applications Include:
 Multivoltage DSPs and Processors
 Portable Battery-Powered Equipment
 Embedded Control Systems
 Intelligent Instruments
 Automotive Systems



TYPICAL OPERATING CIRCUIT





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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description (continued)

The various supervisory circuits are designed to monitor the nominal supply voltage, as shown in the following supply-voltage monitoring table.

SUPPLY-VOLTAGE MONITORING

DEVICE	NOMINAL SUPE	RVISED VOLTAGE	THRESHOLD VOLTAGE (TYP)		
	SENSE1	SENSE2	SENSE1	SENSE2	
TPS3306-15	3.3 V	1.5 V	2.93 V	1.4 V	
TPS3306-18	3.3 V	1.8 V	2.93 V	1.68 V	
TPS3306-20	3.3 V	2 V	2.93 V	1.85 V	
TPS3306-25	3.3 V	2.5 V	2.93 V	2.25 V	
TPS3306-33	5 V	3.3 V	4.55 V	2.93 V	

During power on, $\overline{\text{RESET}}$ is asserted when the supply voltage, V_{DD} , becomes higher than 1.1 V. Thereafter, the supervisory circuits monitor the SENSEn inputs and keep $\overline{\text{RESET}}$ active as long as SENSEn remains below the threshold voltage, V_{IT} .

An internal timer delays the return of the $\overline{\text{RESET}}$ output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d(typ)} = 100$ ms, starts after SENSE1 and SENSE2 inputs have risen above V_{IT} . When the voltage at SENSE1 or SENSE2 input drops below the V_{IT} , the output becomes active (low) again.

The integrated power-fail (PFI) comparator with separate open-drain (PFO) output can be used for low-battery detection, power-fail warning, or for monitoring a power supply other than the main supply.

The TPS3306-xx devices integrate a watchdog timer that is periodically triggered by a positive or negative transition of the watch-dog timer (WDI). When the supervising system fails to retrigger the watchdog circuit within the time-out interval, $t_{t(out)} = 0.50$ s, $\overline{\text{RESET}}$ becomes active for the time period t_d . This event also reinitializes the watchdog timer. Leaving WDI unconnected disables the watchdog.

The TPS3306-xx devices are available in standard 8-pin SO packages.

The TPS3306-xxQ family is characterized for operation over a temperature range of –40°C to 125°C.

AVAILABLE OPTIONS†

_	PACKAGED	TOP-SIDE	
TA	SMALL O	MARKING	
	Tape and reel	TPS3306-15QDRQ1	615Q1
	Tape and reel	TPS3306-18QDRQ1	618Q1
-40°C to 125°C	Tape and reel	TPS3306-20QDRQ1	620Q1
	Tape and reel TPS3306-25QDRQ1		625Q1
	Tape and reel	TPS3306-33QDRQ1	633Q1

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

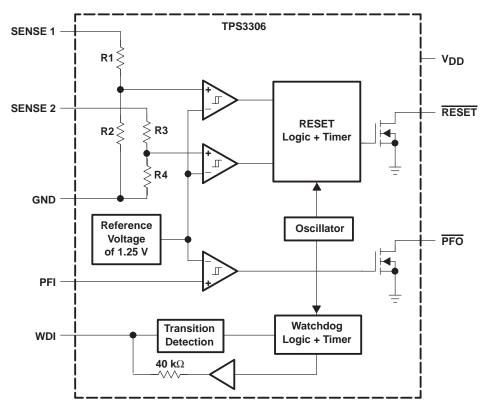
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FUNCTION/TRUTH TABLES

SENSE1 > VIT1	SENSE2 > V _{IT2}	RESET
0	0	L
0	1	L
1	0	L
1	1	Н

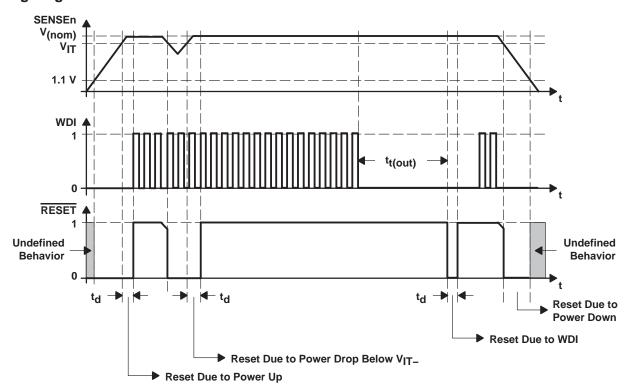
PFI > V _{IT}	PFO	TYPICAL DELAY
0→1	L→H	0.5 μs
1→0	H→L	0.5 μs

functional block diagram



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timing diagram



Terminal Functions

TERMIN	IAL	1/0	DECORPORTION						
NAME	NO.	1/0	DESCRIPTION						
GND	4		Ground						
PFI	3		Power-fail comparator input						
PFO	6	0	Power-fail comparator output, open drain						
RESET	5	0	Active-low reset output, open drain						
SENSE1	1	- 1	Sense voltage 1						
SENSE2	2	1	Sense voltage 2						
WDI	7	I	Watchdog timer input						
V_{DD}	8	I	Supply voltage						

detailed description

watchdog

In a microprocessor- or DSP-based system, it is not only important to supervise the supply voltage, it is also important to ensure correct program execution. The task of a watchdog is to ensure that the program is not stalled in an indefinite loop. The microprocessor, microcontroller, or DSP has to typically toggle the watchdog input (WDI) within 0.8 s to avoid a time-out occurring. Either a low-to-high or a high-to-low transition resets the internal watchdog timer. If the input is unconnected or tied with a high-impedance driver, the watchdog is disabled and is retriggered internally.



saving current while using the watchdog

WDI is internally driven low during the first 7/8 of the watchdog time-out period, then momentarily pulses high, resetting the watchdog counter. For minimum watchdog input current (minimum overall power consumption), leave WDI low for the majority of the watchdog time-out period, pulsing it low-high-low once within 7/8 of the watchdog time-out period to reset the watchdog timer. If, instead, WDI is externally driven high for the majority of the time-out period, a current of 5 V/40 k Ω \approx 125 μ A can flow into WDI.

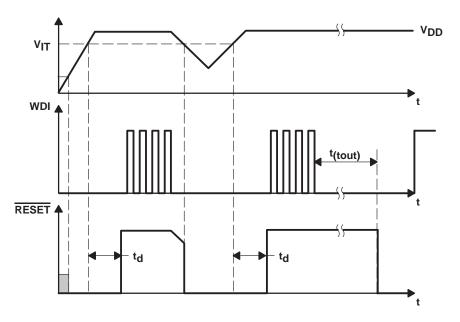


Figure 1. Watchdog Timing

power-fail comparator (PFI and PFO)

An additional comparator is provided to monitor voltages other than the nominal supply voltage. The power-fail-input (PFI) is compared with an internal voltage reference of 1.25 V. If the input voltage falls below the power-fail threshold (V_{PFI}) of 1.25 V (typ), the power-fail output (\overline{PFO}) goes low. If \overline{PFO} goes above 1.25 V plus about 10–mV hysteresis, the output returns to high. By connecting two external resistors, it is possible to supervise any voltages above 1.25 V. The sum of both resistors should be approximately 1 M Ω , to minimize power consumption and also to ensure that the current in the PFI pin can be neglected compared with the current through the resistor network. The tolerance of the external resistors should be not more than 1% to ensure minimal variation of sensed voltage. If the power-fail comparator is unused, connect PFI to ground and leave \overline{PFO} unconnected.

$$V_{PFI,trip} = 1.25 \text{ V} \times \frac{R_1 + R_2}{R_2}$$

$$R1 \\ 1\%$$

$$R2 \\ 1\%$$

$$R2 \\ TPS3306 \\ GND$$

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note1): V _{DD}	7 V
	0.3 V to 7 V
Maximum low output current, I _{OL}	5 mA
Maximum high output current, IOH	–5 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_O$	/ _{DD}) ±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A .	–40°C to 125°C
Storage temperature range, T _{stq}	–65°C to 150°C
Soldering temperature	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation, the device must not be operated at 7 V for more than t = 1000 h continuously.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	
D	725 mW	5.8 mW/°C	464 mW	377 mW	

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V _{DD}	2.7	6	V
Input voltage at WDI and PFI, VI	0	V _{DD} + 0.3	V
Input voltage at SENSE1 and SENSE2, VI	0	$(V_{DD} + 0.3)V_{IT}/1.25 V$	V
High-level input voltage at WDI, VIH	$0.7 \times V_{DD}$		V
Low-level input voltage at WDI, V _{IL}		$0.3 \times V_{DD}$	V
Operating free-air temperature range, TA	-40	125	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT			
			V_{DD} = 2.7 V to 6 V, I_{OL} = 20 μ A			0.2			
V_{OL}	Low-level output voltage	RESET, PFO	V _{DD} = 3.3 V, I _{OL} = 2 mA			0.4	V		
			$V_{DD} = 6 V$, $I_{OL} = 3 \text{ mA}$			0.4			
	Power-up reset voltage (see Note 2)		$V_{DD} \ge 1.1 \text{ V}, \qquad I_{OL} = 20 \mu\text{A}$			0.4	V		
				1.35	1.4	1.44			
				1.62	1.68	1.74			
		VSENSE1,	[,, -,,, -,,	1.79	1.85	1.91			
VIT	Negative-going input threshold voltage	VSENSE2	V _{DD} = 2.7 V to 6 V,	2.18	2.25	2.34	V		
	(see Note 3)		$T_A = -40^{\circ}C \text{ to } 125^{\circ}C$	2.84	2.93	3.04	, ,		
				4.44	4.55	4.68			
		PFI		1.2	1.25	1.3			
		PFI	V _{IT} = 1.25 V		10				
			V _{IT} = 1.4 V		15				
			V _{IT} = 1.68 V		15				
V_{hys}	Hysteresis		V _{IT} = 1.86 V		20		mV		
,0	•	VSENSEn	V _{IT} = 2.25 V		20				
			V _{IT} = 2.93 V		30				
			V _{IT} = 4.55 V		40				
I _{H(AV)}	Average high-level input current	WDI	WDI = V _{DD} = 6 V, Time average (dc = 88%)		100	150	μΑ		
I _{L(AV)}	Average low-level input current	WDI	WDI = 0 V, $V_{DD} = 6 V$, Time average (dc = 12%)		-15	-20	μΑ		
		WDI	WDI = V _{DD} = 6 V		120	170			
lΗ	High-level input current	SENSE1	VSENSE1 = VDD = 6 V		5	10	μΑ		
••	-	SENSE2	VSENSE2 = VDD = 6 V		6	10	•		
ΙL	Low-level input current	WDI	WDI = 0 V, V _{DD} = 6 V		-120	-170	μΑ		
- <u>-</u>	Input current	PFI	$V_{DD} = 6 \text{ V}, 0 \text{ V} \le V_{I} \le V_{DD}$	-30		30	nA		
I _{DD}	Supply current				15	40	μΑ		
Ci	Input capacitance	$V_I = 0 \ V \text{ to } V_{DD}$		10		pF			

NOTES: 2. The lowest supply voltage at which $\overline{\text{RESET}}$ becomes active. t_f , $V_{DD} \ge 15 \,\mu\text{s/V}$.

timing requirements at V_{DD} = 2.7 V to 6 V, R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

PARAMETER			TE	MIN	MAX	UNIT	
	Dulas width	SENSEn	V _{SENSENL} = V _{IT} - 0.2 V,	VSENSEnH = VIT + 0.2 V	6		μs
t _w Pulse width	WDI	$V_{IH} = 0.7 \times V_{DD}$	$V_{IL} = 0.3 \times V_{DD}$	100		ns	

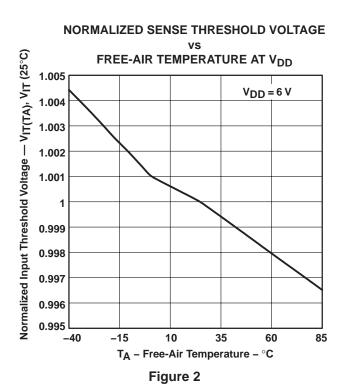
^{3.} To ensure best stability of the threshold voltage, a bypass capacitor (ceramic 0.1 μ F) should be placed close to the supply terminals.

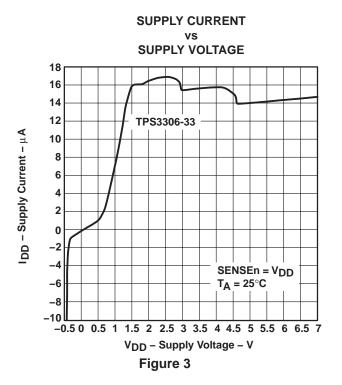
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switching characteristics at V_{DD} = 2.7 V to 6 V, R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _t (out)	Watchdog time-out			V _I (SENSEn) ≥ V _{IT} + 0.2 V, See timing diagram	0.5	0.8	1.2	s
t _d	Delay time			VI(SENSEn) ≥ VIT + 0.2 V, See timing diagram	70	100	140	ms
tPHL	Propagation (delay) time, high- to low-level output	SENSEn	RESET	V _{IH} = V _{IT} + 0.2 V, V _{IL} = V _{IT} - 0.2 V		1	5	μs
tPHL	Propagation (delay) time, high- to low-level output		250			0.5		
tpLH	Propagation (delay) time, low- to high-level output	PFI	PFO			0.5	1	μs

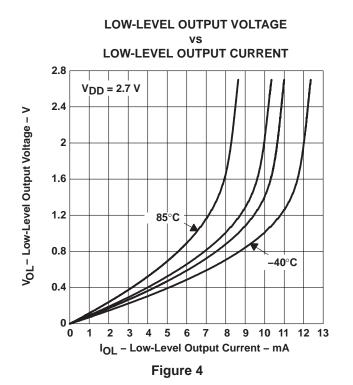
TYPICAL CHARACTERISTICS

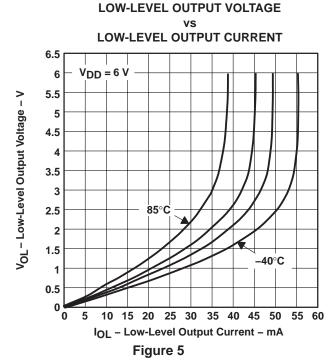




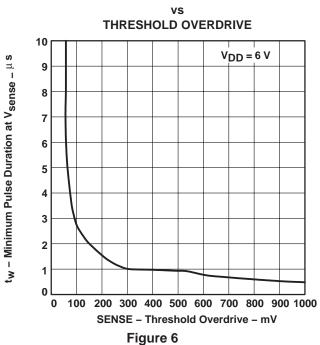
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TYPICAL CHARACTERISTICS





MINIMUM PULSE DURATION AT SENSE



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty		Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS3306-15QDRG4Q1	LIFEBUY	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	615Q1	
TPS3306-15QDRQ1	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	615Q1	Samples
TPS3306-18QDRG4Q1	LIFEBUY	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	618Q1	
TPS3306-18QDRQ1	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	618Q1	Samples
TPS3306-25QDRG4Q1	LIFEBUY	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	625Q1	
TPS3306-33QDRG4Q1	LIFEBUY	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	633Q1	
TPS3306-33QDRQ1	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	633Q1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF TPS3306-Q1:

Catalog: TPS3306

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com 16-Jan-2023

TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO PI BO Cavity A0

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3306-15QDRG4Q1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS3306-15QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS3306-18QDRG4Q1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS3306-18QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS3306-25QDRG4Q1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS3306-33QDRG4Q1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS3306-33QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3306-15QDRG4Q1	SOIC	D	8	2500	350.0	350.0	43.0
TPS3306-15QDRQ1	SOIC	D	8	2500	350.0	350.0	43.0
TPS3306-18QDRG4Q1	SOIC	D	8	2500	350.0	350.0	43.0
TPS3306-18QDRQ1	SOIC	D	8	2500	350.0	350.0	43.0
TPS3306-25QDRG4Q1	SOIC	D	8	2500	350.0	350.0	43.0
TPS3306-33QDRG4Q1	SOIC	D	8	2500	350.0	350.0	43.0
TPS3306-33QDRQ1	SOIC	D	8	2500	350.0	350.0	43.0



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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